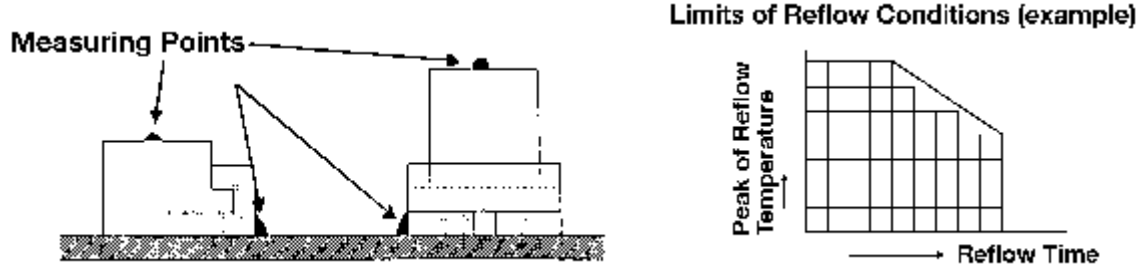


Reflow Soldering for Surface Mount Capacitors

Installation of Non-Solid and Solid Aluminum Electrolytic Capacitors

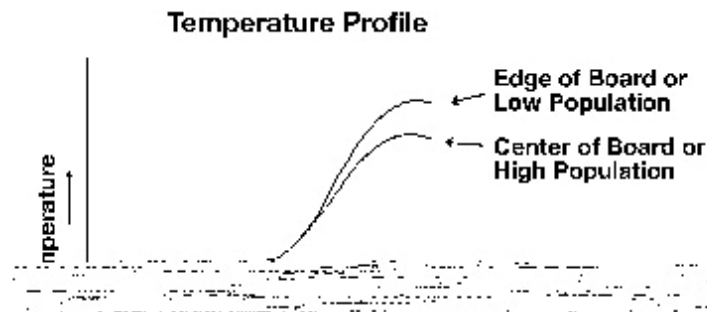
Explanatory Notes

1. To determine a reflow temperature profile, measure the temperatures at specific points, and then follow conditions specified in the product literature.



2. Temperature distribution to capacitors on a PC board varies due to the following:
 - o Material, size and thickness of the PC board.
 - o Location (center or perimeter) on the PC board.
 - o Quantity of components.
 - o Size of adjacent components.

After checking temperature profiles, set the time and temperature conditions within the limits specified in the product literature.



3. Because the first reflow soldering process increases the internal temperature and gas pressure of a capacitor, a second reflow should be avoided. However, if a second reflow is necessary, consult United Chemi-Con for soldering conditions.

Precaution

1. Reflow soldering conditions (preheat, solder temperature and exposure time) should be within the limits specified in the product literature.
2. When setting temperature for the infrared reflow furnace, consider that the color and material of a capacitor vary in their infrared absorption.

3. Avoid reflow soldering more than once. Consult United Chemi-Con for reflow soldering a second time.
4. If reworking a PC board, do not re-use capacitors that were soldered and then removed from the PC board. Remove old flux on the surface of the PC board and install new capacitors using a soldering iron within specified limits in the product literature.